



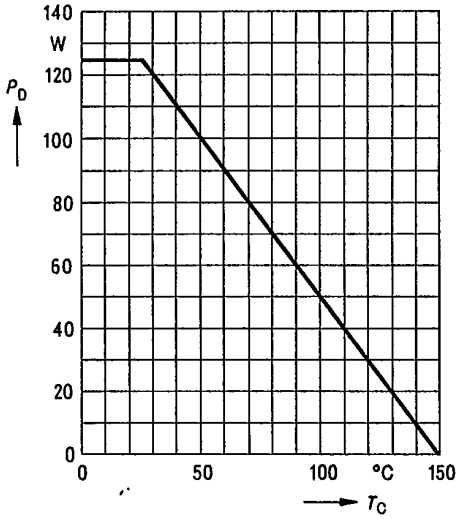
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**Electrical characteristics**(at  $T_j = 25^\circ\text{C}$  unless otherwise specified)

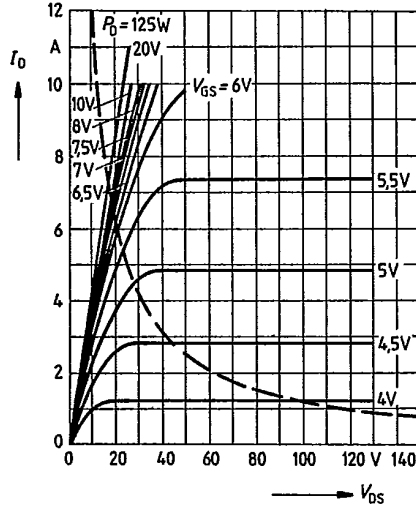
Description	Symbol	Characteristics			Unit	Conditions
		min.	typ.	max.		
<b>Static ratings</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	1000	—	—	V	$V_{GS} = 0V$ $I_D = 0,25mA$
Gate threshold voltage	$V_{GS(th)}$	2,1	3,0	4,0		$V_{DS} = V_{GS}$ $I_D = 1mA$
Zero gate voltage drain current	$I_{DSS}$	—	20	250	$\mu A$	$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ $V_{DS} = 1000V$ $V_{GS} = 0V$
Gate-source leakage current	$I_{GSS}$	—	10	100	nA	$V_{GS} = 20V$ $V_{DS} = 0V$
Drain-source on-resistance	$R_{DS(on)}$	—	2,3	2,6	$\Omega$	$V_{GS} = 10V$ $I_D = 3,5A$
<b>Dynamic ratings</b>						
Forward transconductance	$g_{fs}$	1,4	4,0	—	S	$V_{DS} = 25V$ $I_D = 3,5A$
Input capacitance	$C_{iss}$	—	3,9	5,0	nF	$V_{GS} = 0V$
Output capacitance	$C_{oss}$	—	180	300	pF	$V_{DS} = 25V$ $f = 1MHz$
Reverse transfer capacitance	$C_{riss}$	—	70	120		
Turn-on time $t_{on}$ ( $t_{on} = t_{d(on)} + t_r$ )	$t_{d(on)}$	—	60	90	ns	$V_{CC} = 30V$ $I_D = 2,4A$ $V_{GS} = 10V$ $R_{GS} = 50\Omega$
	$t_r$	—	90	140		
Turn-off time $t_{off}$ ( $t_{off} = t_{d(off)} + t_f$ )	$t_{d(off)}$	—	330	430		
	$t_f$	—	110	140		
<b>Fast-recovery reverse diode</b>						
Continuous reverse drain current	$I_{DR}$	—	—	4,9	A	$T_C = 25^\circ\text{C}$
Pulsed reverse drain current	$I_{DRM}$	—	—	19		
Diode forward on-voltage	$V_{SD}$	—	1,35	1,60	V	$I_F = 2 \times I_{DR}$ $V_{GS} = 0V, T_j = 25^\circ\text{C}$
Reverse recovery time	$t_{rr}$	—	—	250	ns	$T_j = 25^\circ\text{C}$
		—	—	300		$T_j = 150^\circ\text{C}$
Reverse recovery charge	$Q_{rr}$	—	—	1,2	$\mu C$	$T_j = 25^\circ\text{C}$
		—	—	5,0		$T_j = 150^\circ\text{C}$
Repetitive peak reverse current	$I_{RRM}$	—	—	—	A	$T_j = 25^\circ\text{C}$
		—	15	—		$T_j = 150^\circ\text{C}$

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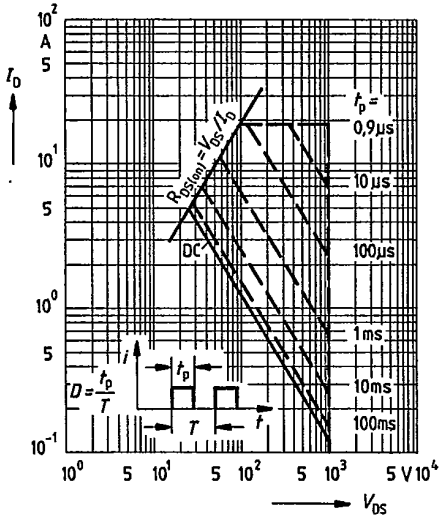
Power dissipation  $P_D = f(T_C)$



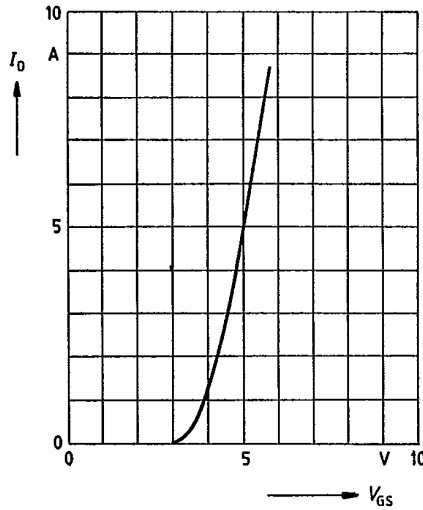
Typical output characteristics  $I_D = f(V_{DS})$   
parameter: 80  $\mu$ s pulse test,  
 $T_J = 25^\circ\text{C}$



Safe operating area  $I_D = f(V_{DS})$   
parameter:  $D = 0.01$ ,  $T_C = 25^\circ\text{C}$



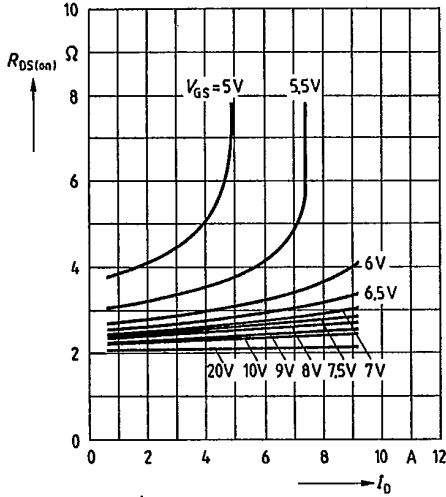
Typical transfer characteristic  $I_D = f(V_{GS})$   
parameter: 80  $\mu$ s pulse test,  
 $V_{DS} = 25\text{V}$ ,  $T_J = 25^\circ\text{C}$



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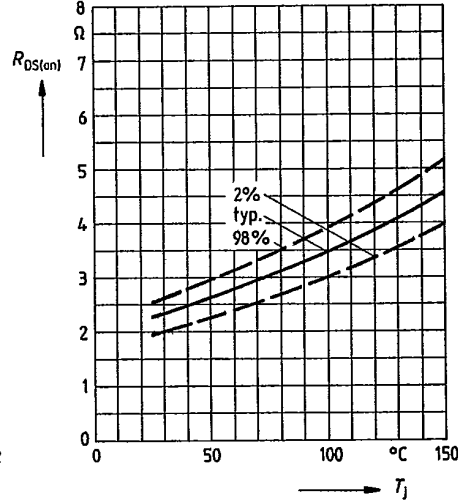
**Typical drain-source on-state resistance**

$R_{DS(on)} = f(I_D)$   
 parameter:  $V_{GS} = 5V, T_j = 25^\circ C$



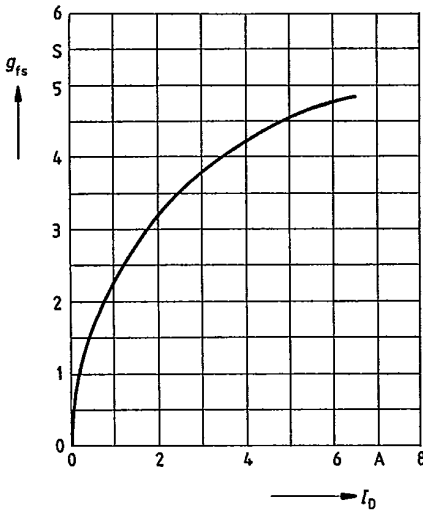
**Drain-source on-state resistance**

$R_{DS(on)} = f(T_j)$   
 parameter:  $I_D = 3.5A, V_{GS} = 10V$   
 (spread)



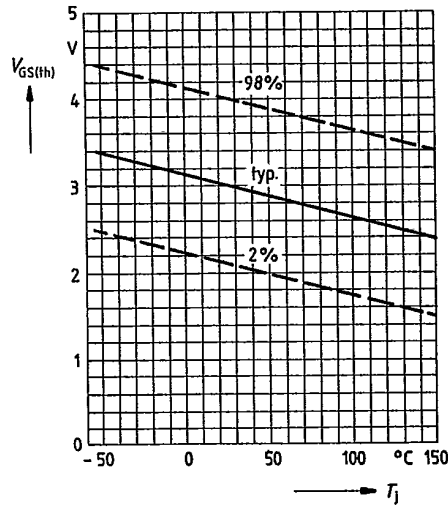
**Typical transconductance**

$g_{fs} = f(I_D)$   
 parameter: 80  $\mu s$  pulse test,  
 $V_{DS} = 25V, T_j = 25^\circ C$



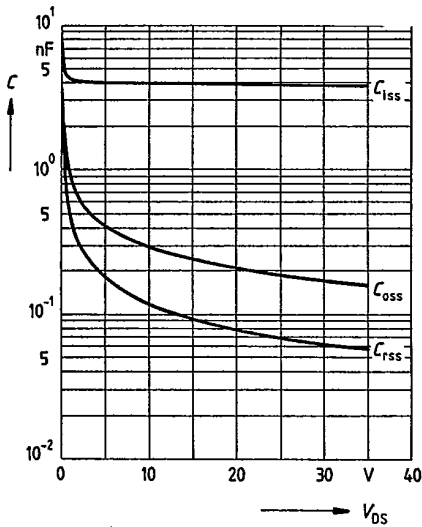
**Gate threshold voltage**

$V_{GS(th)} = f(T_j)$   
 parameter:  $V_{DS} = V_{GS}, I_D = 1mA$   
 (spread)

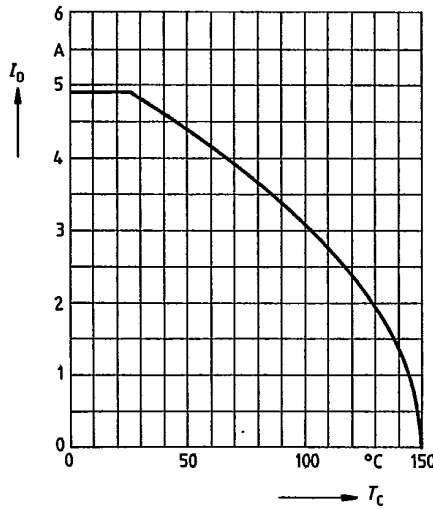


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Typical capacitances  $C = f(V_{DS})$   
parameter:  $V_{GS} = 0, f = 1\text{MHz}$

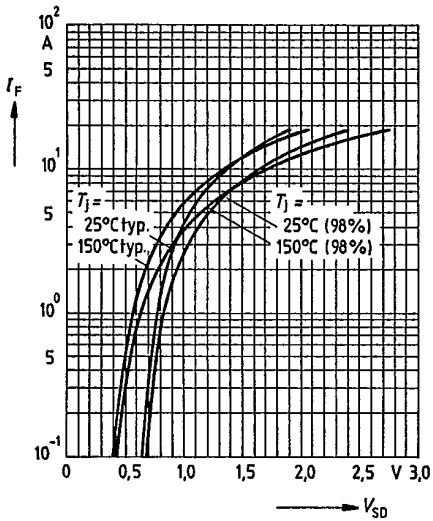


Continuous drain current  $I_D = f(T_C)$   
parameter:  $V_{GS} \geq 10\text{V}$



Forward characteristic of reverse diode

$I_F = f(V_{SD})$   
parameter:  $T_j, t_p = 80 \mu\text{s}$   
(spread)



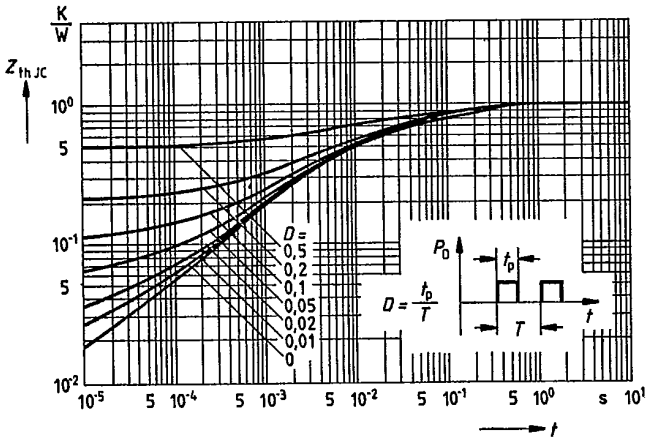
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Transient thermal impedance  $Z_{thJC} = f(t)$   
parameter:  $D = t_p/T$



Typical gate-charge  $V_{GS} = f(Q_{Gate})$   
parameter:  $I_{D\ pulse} = 8A$

